



JUL 05 2006

<b>CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)</b>			Docket No. YOM-0051
Applicant(s): Bum-Gee BAEK, et al.			
Application No. 10/653,556	Filing Date 9-2-2003	Examiner Crane, Sara W.	Group Art Unit 2811
Invention: CONTACT STRUCTURE OF SEMICONDUCTOR DEVICE, MANUFACTURING METHOD THEREOF, THIN FILM TRANSISTOR ARRAY PANEL INCLUDING CONTACT STRUCTURE, AND MANUFACTURING METHOD THEREOF			
<p>I hereby certify that this <u>Amendment Transmittal Letter (1 page) &amp; Response to Office Action (6 pages)</u> (Identify type of correspondence)</p> <p>is being facsimile transmitted to the United States Patent and Trademark Office (Fax, No. <u>571-273-8300</u>)</p> <p>on <u>July 5, 2006</u> (Date)</p> <p style="text-align: right;"><u>Tammie Lanthier</u> (Typed or Printed Name of Person Signing Certificate)</p> <p style="text-align: right;"> (Signature)</p> <p style="text-align: center;">Note: Each paper must have its own certificate of mailing.</p>			

P18/REV02

JUL 05 2006

<b>AMENDMENT TRANSMITTAL LETTER (Large Entity)</b>				Docket No. YOM-0051	
Applicant(s): Bum-Gee BAEK, et al.					
Application No. 10/653,556	Filing Date 9-2-2003	Examiner Crane, Sara W.	Customer No. 23413	Group Art Unit 2811	Confirmation No. 3225
Invention: <b>CONTACT STRUCTURE OF SEMICONDUCTOR DEVICE, MANUFACTURING METHOD THEREOF, THIN FILM TRANSISTOR ARRAY PANEL INCLUDING CONTACT STRUCTURE, AND MANUFACTURING METHOD THEREOF</b>					
<b><u>COMMISSIONER FOR PATENTS:</u></b>					
Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below.					
<b>CLAIMS AS AMENDED</b>					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	17 -	36 -	0	x \$50.00	\$0.00
INDEP. CLAIMS	2 -	6 -	0	x \$200.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
<b>TOTAL ADDITIONAL FEE FOR THIS AMENDMENT</b>					<b>\$0.00</b>
<div style="display: flex; justify-content: space-between;"><div><input checked="" type="checkbox"/> No additional fee is required for amendment. <input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of _____ <input type="checkbox"/> A check in the amount of _____ to cover the filing fee is enclosed. <input checked="" type="checkbox"/> The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account 06-1130 <div style="margin-left: 20px;"><input checked="" type="checkbox"/> Any additional filing fees required under 37 C.F.R. 1.16. <input checked="" type="checkbox"/> Any patent application processing fees under 37 CFR 1.17.</div><input type="checkbox"/> Payment by credit card. Form PTO-2038.</div><div><b>WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.</b></div></div>					
<div style="text-align: center;"> Signature</div> <div>James J. Merrick Reg. No. 43,801 Cantor Colburn LLP 55 Griffin Road South Bloomfield, CT 06002 Telephone: (860) 286-2929 Fax: (860) 286-0115</div>			Dated: July 5, 2006		
cc:			<div>I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1460, Alexandria, VA 22313-1460" [37 CFR 1.8(a)] on _____ (Date)</div> <div style="border-top: 1px solid black; margin-top: 10px;">Signature of Person Mailing Correspondence</div> <div style="border-top: 1px solid black; margin-top: 10px;">Typed or Printed Name of Person Mailing Correspondence</div>		

P11LARGE/REV09

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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: BUM-GEE BAEK, ET AL. )  
Serial No.: 10/653,556 ) Group Art Unit:  
Filed: September 2, 2003 ) 2811  
For: CONTACT STRUCTURE OF ) Examiner:  
SEMICONDUCTOR DEVICE, ) CRANE, Sara W.  
MANUFACTURING METHOD THEREOF, )  
THIN FILM TRANSISTOR ARRAY PANEL )  
INCLUDING CONTACT STRUCTURE, AND )  
MANUFACTURING METHOD THEREOF )

## RESPONSE TO OFFICE ACTION

Sir:

In response to the Office Action mailed April 5, 2006, Applicants request reconsideration in view of the following amendments and remarks for entry in the above-identified application.

Amendments to the claims are reflected in the listing of claims, which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.